



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2827
Examiner: J. ALCALA

In Re PATENT APPLICATION Of:

Applicant(s): Mark J. BAILEY et al.
Serial No.: 09/651,334
Filed: August 31, 2000
For: ENHANCED SURFACE LAMINAR
CIRCUIT BOARD
Docket No.: ROC9-2000-0158-IBM-191

AMENDMENT

February 12, 2003

Assistant Commissioner of Patents
Washington, D.C. 20231

Sir:

In response to the Examiner's Action mailed on December 4, 2002, please
amend the application as follows:

IN THE CLAIMS:

Claim 1. (Amended) A surface laminar circuit board, comprising:
an insulating layer;
a conductive layer disposed on an upper surface of said insulating layer, said
conductive layer having a hole formed therein;
a dielectric layer disposed on an upper surface of the conductive layer; and
a conductive pad having [a majority] over 50% thereof within an area defined by
an outer periphery of the hole, said conductive pad being for receiving a surface
mounted component thereon.

FEE ENCLOSED:\$
Please charge any further
fee to our Deposit Account
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